

Abstract

The present invention provides a curable resin composition exhibiting low dielectric characteristics, and a cured product thereof. The curable resin composition contains a compound represented by formula (1) and an azo compound represented by formula (2). In formula (1), a plurality of Rs each independently represent a hydrogen atom, a C1-C10 hydrocarbon group, or a C1-C10 halogenated alkyl group. p and r each represent an integer of 0-4, q represents an integer of 0-3, and n is an average value for number of repetitions and satisfies $1 \leq n \leq 20$. In formula (2), R₁ and R₂ each independently represent a hydrogen atom or a C1-C20 hydrocarbon group.

